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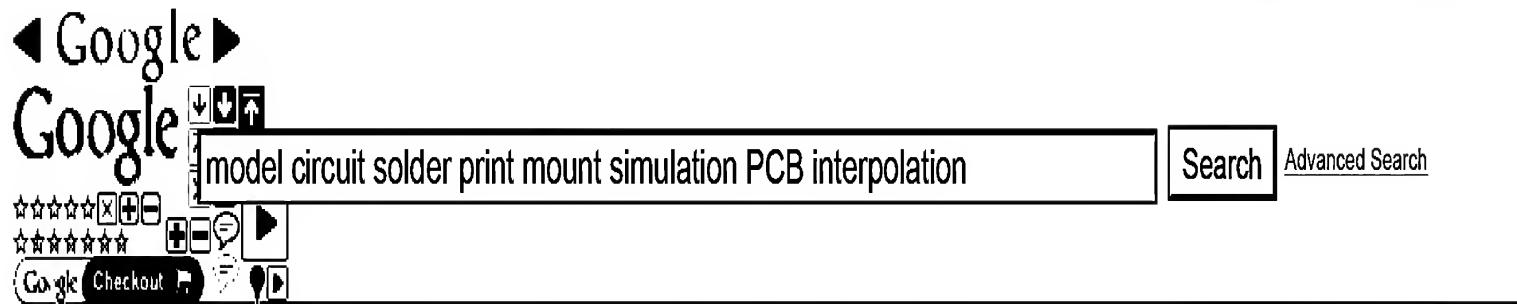
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 ... In this method, component leads are **soldered** on the surface of the board, rather than being  
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YY Su, K Srihari, CR Emerson - Computers & industrial engineering, 1997 - Elsevier  
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Critical factors affecting paste flow during the stencil **printing** of **solder paste**

R Durairaj, TA Ngutu, NN Ekere - **Soldering** and Surface Mount ..., 2001 - emeraldinsight.com  
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J Glazer, PA Kramer, JW Morris Jr - **Circuit** World, 1992 - emeraldinsight.com

... However, in joints that were subjected to the adjacent rework **simulation** treatment of 170°C/ 2 min., these small voids coalesced into much larger ... **Circuit** World Vol.18 No.4, 1992 4 Foster, FG, 'Embrittlement of **Solder** by Gold from Plated Surfaces,' ASTM STP 319, p. 13 (1963). ...

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BA Zahn - Proceedings of the 9th International ANSYS ..., 2000 - ansys.net

... geometry's including nodes and elements are selected, and finally the local.nd file is used to locate and **interpolate** global model ... 5. FATIGUE MODEL **SIMULATION** RESULTS ... This is certainly the case for the -Z (ball/pcb) **solder** joint where the amount of plastic work per cycle is ...Cited by 19 - Related articles - View as HTML - All 2 versions**Guidelines to select underfills for flip chip on board assemblies and compliant ...**JH Okura, S Shetty, B Ramakrishnan, A Dasgupta, ... - *Microelectronics* ..., 2000 - Elsevier... extreme values of the two parameters (CTE and stiffness) and the results are **interpolated** for intermediate ... in the flex CSP technology the die is very close to the **PCB**, the mechanical ... interposer CTE and stiffness on fatigue life of the **solder** joints, through modeling and **simulation** ...Cited by 11 - Related articles - BL Direct - All 3 versions**[PDF]** •Finite Element Modeling of a BGA Package Subjected to Thermal and Power ...

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... It is to this end that META (Microelectronic Hhermal Analyser), the **simulation** routine presented in ... across the **PCB** using this ap- proximation, it was shown that the **PCB** thermal resistance ... of the delay function on the type of convective heat transfer, an **interpolation** between the ...

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K Srihari, JA Cecil, CR Emerson - The International Journal of Advanced ..., 1994 - Springer

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SH Mannan, NN Ekere, I Ismail, MA Currie - Journal of Materials Science: ..., 1995 - Springer

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J Glazer, PA Kramer, JW Morris Jr - Circuit World, 1992 - emeraldinsight.com

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... the numbers and types of the various passive and active surface **mounted** components on ... systems to its customers follows the flow in Figure 1. Line **Simulation** Inputs Spreadsheet ... | Cost Related Inputs Economic Analysis Figure 1. Components in **PCB Assembly** Line Proposal ...

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... In this method, component leads are **soldered** on the surface of the board, rather than ... 20 Feldmann, K., Franke, J. and Rothhaupt, A. (1994) 'Optimization and **simulation** of the ... K. (1993) 'A solution methodology for the multiple batch surface **mount PCB** placement sequence ...

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SM Bryant, KH Loewenthal - US Patent 5,751,910, 1998 - Google Patents

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JK Berry - 1996 - [books.google.com](#)... E-mail: [books@gisworld.com](mailto:books@gisworld.com) Edited by John Hughes Designed and composed by Wade SmithProject managed by Bea Ferrigno Second **Printing**. ... For example, a geographic distribution(3-D surface) of **PCB** concentra- tions in an aquifer can be **interpolated** from water ...[Cited by 50](#) - [Related articles](#) - [All 5 versions](#)

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... object surface. FIG. 2A is a cross-sectional view of a particular embodiment of an

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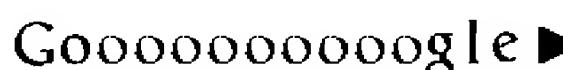
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